

ABSTRACT

A method for forming a sensor including the steps of providing a base wafer and forming a sensor cavity in the base wafer. The method further includes the step of coupling a diaphragm wafer to the base wafer, the diaphragm wafer including a diaphragm portion and a sacrificial portion. The diaphragm wafer is coupled to the base wafer such the diaphragm portion generally covers the sensor cavity. The method further includes the steps of reducing the thickness of the diaphragm wafer by removing the sacrificial portion, and forming or locating at least one piezo resistive portion on the diaphragm portion.

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